

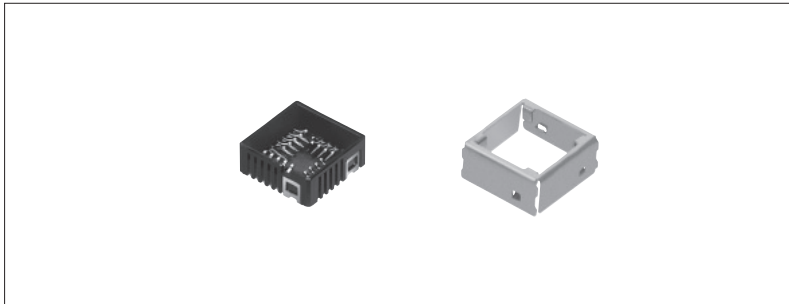
# Connector for CMOS Camera Module

SCKA Series



Compact size achieved from thin body-forming molding.

- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For W-SIM
- For Memory Stick Micro™
- For Memory Stick™
- Combine Type
- For Compact Flash™
- For CMOS Camera Module



## Typical Specifications

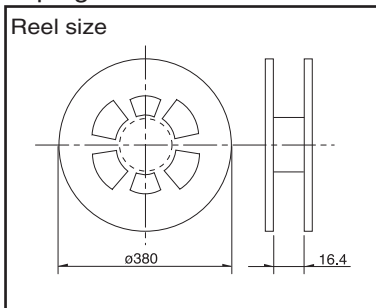
Items		Specifications
Dimensions	6× 6mm module type	7× 7× 3.1mm
Structure	Mounting system	Surface mounting type
Performance	Operating temperature range	-25 °C to +85 °C
	Voltage proof	100V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycles	10cycles

## Product Line

Items	Product	Packing system	Minimum packing unit (pcs.)	Product No.	Drawing No.
6× 6mm module type	Connector	Taping	2,000	SCKA2A0100	1
	Cover		5,000	JSCKA0002A	2

## Packing Specifications

Taping Unit:mm



Product No.	Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing		
SCKA2A0100	2,000	4,000	12,000	16	420×410×187

Bulk

Product No.	Number of packages (pcs.)		Export package measurements (mm)
	1 case /Japan	1 case /export packing	
JSCKA0002A	5,000	10,000	400×288×161



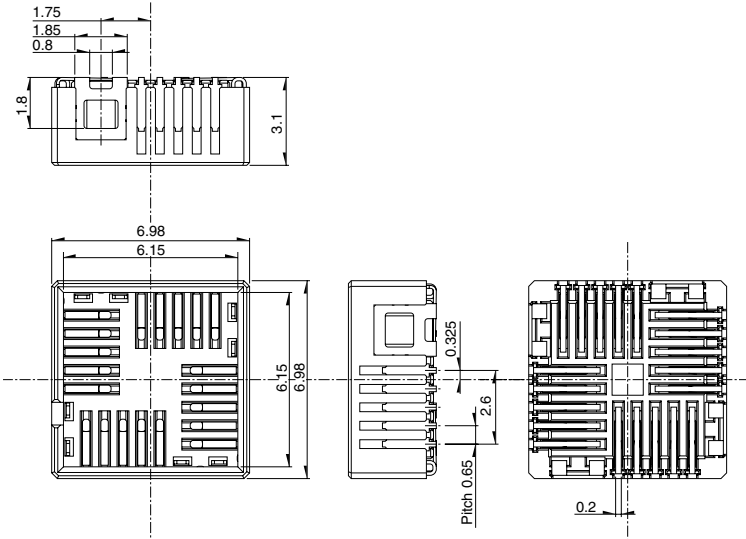
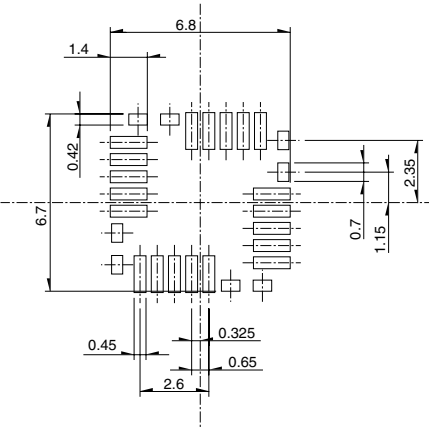
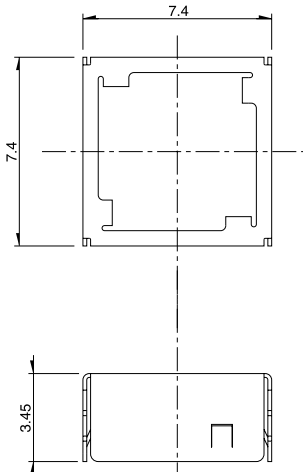
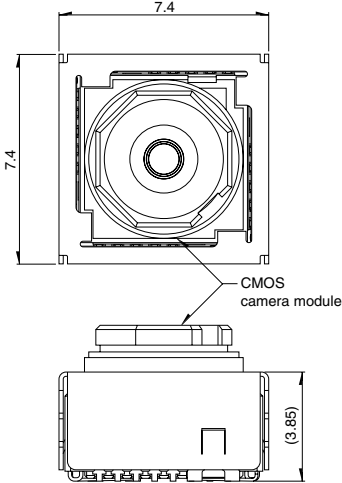
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**ALPS**

**Dimensions**  
6×6mm module type

Unit:mm

No.	Style	
1	<p><b>Connector</b></p> 	
	<p>PC board mounting hole dimensions (Viewed from the mounting face side)</p>	
		
2	<p><b>Style</b></p>	<p><b>Connector/Cover combination diagram (Reference)</b></p>
	<p><b>Cover</b></p> 	 <p>CMOS camera module</p>

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

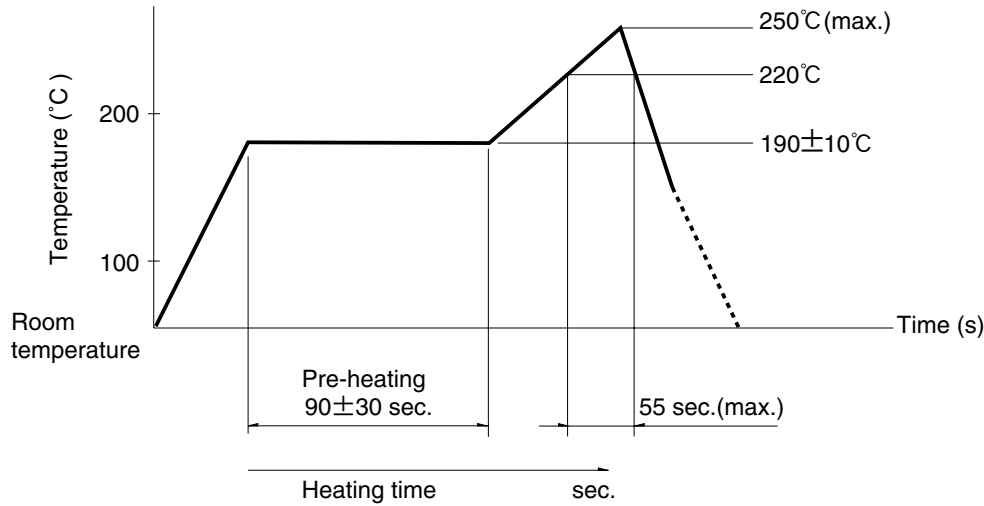
For Compact Flash™

For CMOS Camera Module

## Soldering Conditions

### Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2  $\phi$  CA (K) or CC (T) at soldering portion.
3. Temperature profile



## Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.

For  
SD Memory  
CardFor  
microSD™  
CardFor  
SIM Card  
8pinsFor  
W-SIMFor  
Memory  
Stick Micro™For  
Memory  
Stick™

Combine Type

For  
Compact  
Flash™For CMOS  
Camera Module